

Numerical Modeling of Resistance Welding Process in Joining of Thermoplastic Composite Materials Using Comsol Multiphysics

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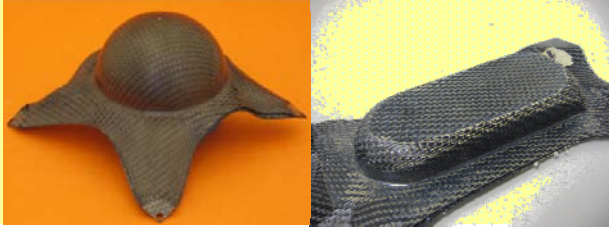


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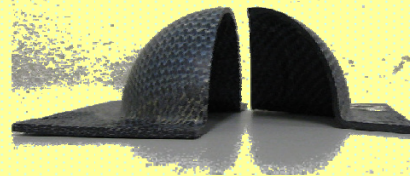
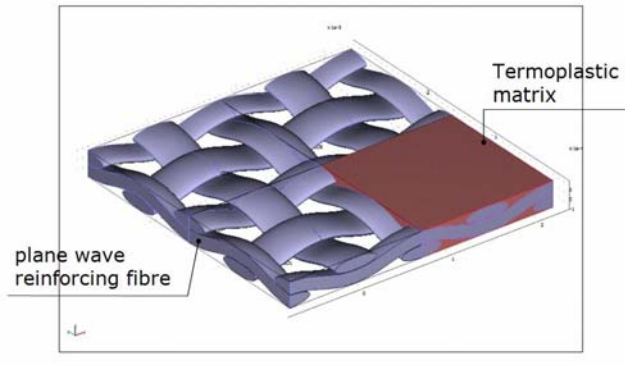
OBJECTIVE

To estimate the mean parameters influence and verify the **joining feasibility** in the **resistance welding** of two thermoplastic composite (TPC) parts

THE THERMOPLASTIC COMPOSITES (TPC)



Are made of reinforced fibres in a thermoplastic resin



ADVANTAGES:

- I. the TPC in laminate form can be re-heating and successively formed
- II. the resin in the TPC laminate can be re-heating and utilized to joint more TPC parts

DISADVANTAGE:

- I. relatively low glass transition temperature for thermoplastic resins
- II. the friction in the fibres reduce the layers sliding consequently the TPC formability to any part shapes

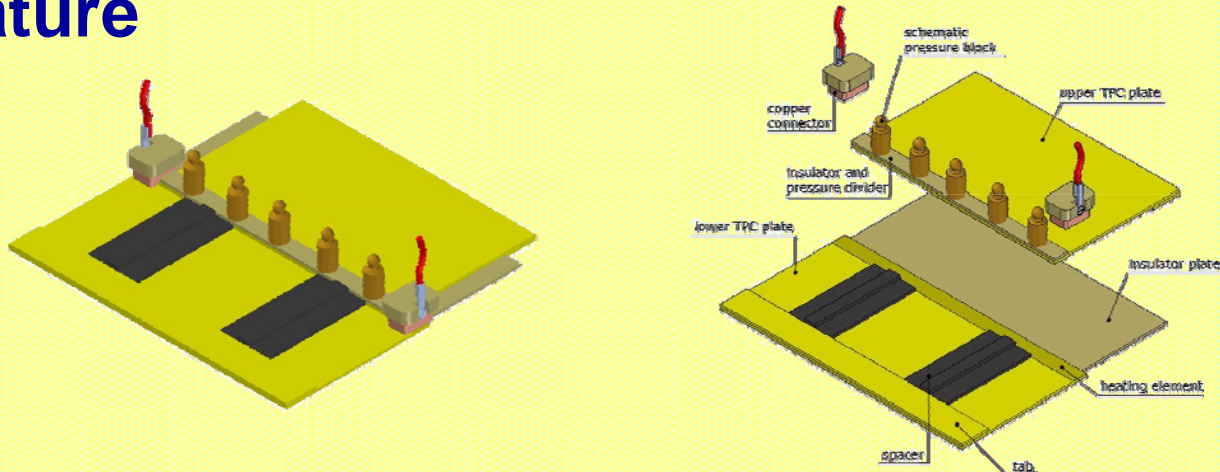
JOINING TECHNOLOGY IN TPC PARTS

The fusion-bonding technology for the TPC parts take advantage from the repeatability melting proces for the resin phase

- a. *INDUCTION WELDING (IW)*
 - No limit in the overlapping length
 - Problem with the **magnetic field** interaction in the surround of the joining device
 - Possible contamination dependently by the conductive media
- b. *RESISTANCE WELDING (RW)*
 - Easy and fast to realize
 - Limitation in the overlapping joint length
 - Possible contamination dependently by the conductive media
- c. *ULTRASONIC WELDING (UW)*
 - No need conductive media
 - Risk of fibre disruption at the interface under the large deformation
- d. *ADHESIVE BONDING (AB)*
 - Thermoplastic composite surfaces are usually too low superficial energy
 - Cure time

THERMOPLASTIC RESISTANCE WELDING PROCESS

The Joule effect in a conductive media heating up the thermoplastic resin above the matrix melting temperature

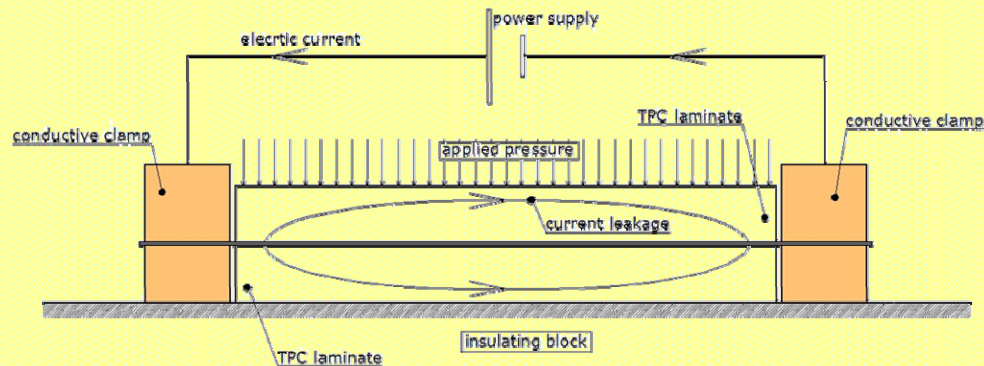


a. **METAL MESH** – lack of homogeneity

CONDUCTIVE MEDIA

b. **CARBON FIBER** – homogeneity in CFR
THERMOPLASTIC composite materials

TPC RESISTANCE WELDING PROCESS: THE PARAMETERS



INFLUENCING PARAMETERS

- TIME PROCESS
- ELECTRICAL POWER DENSITY LEVEL
- EXTERNAL APPLIED LOAD

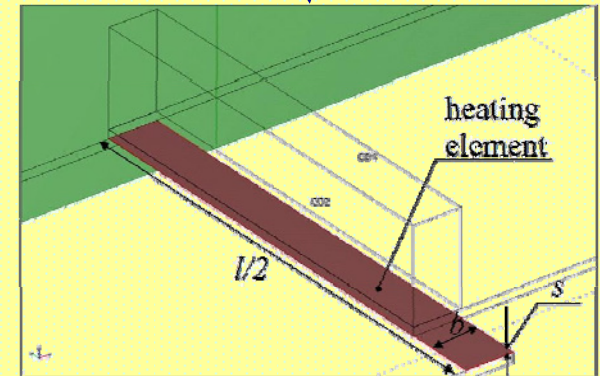
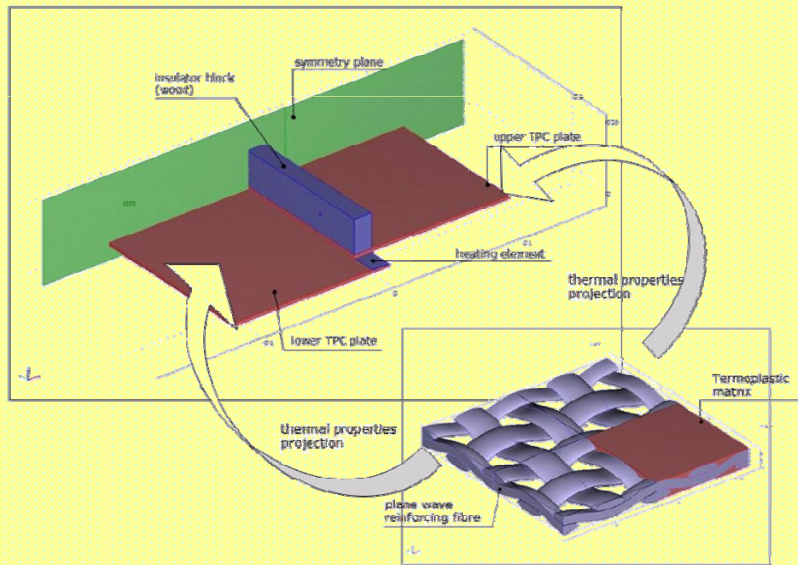
TPC RESISTANCE WELDING PROCESS: THE NUMERICAL MODEL

THERMAL CONDUCTIVITY TPC
LAMINATE MODEL



JOULE INDUCING HEATING

$$\dot{Q} = \frac{(R \cdot I^2)}{b \cdot l \cdot s}$$



RW PROCESS
SIMULATION

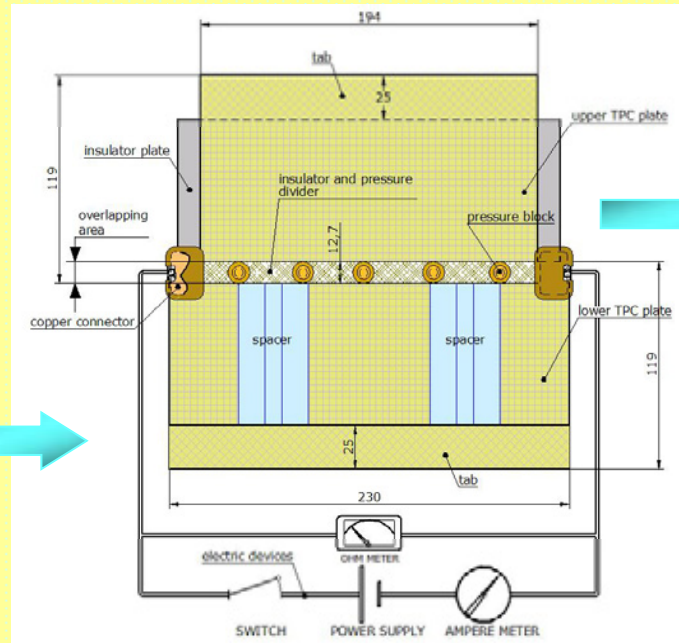
HEAT TRANSFER
PROBLEM

TPC RESISTANCE WELDING PROCESS: THE MODEL GEOMETRY

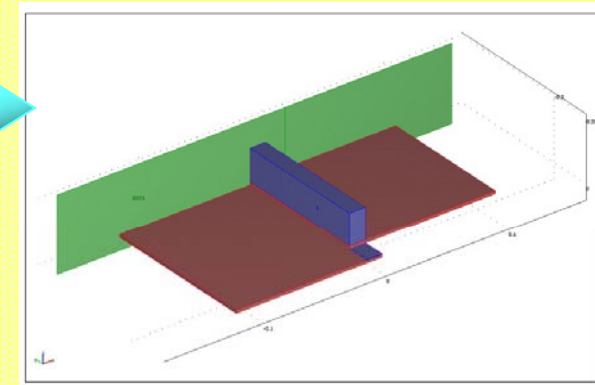
The model geometry was build up on the experimental configuration employed to test the RW process on TPC laminate



**EXPERIMENTAL
CONFIGURATION**



**GEOMETRICAL
DIMENSIONS**



**NUMERICAL
MODEL**

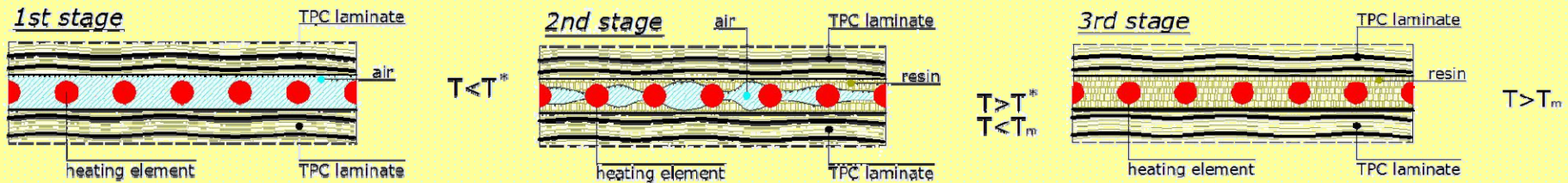
TPC RESISTANCE WELDING PROCESS: THE SIMULATION PARAMETERS

- parametric analysis was carried out using different electric power density coupled with longer or shorter time process
- 2.1 mm thick eight plies polyphenylene sulphide (PPS) reinforced by glass plane wave fabric were simulated using the parameters of the experimental investigation

<i>Simulated process</i>	<i>Power density level</i>	<i>Pressure process</i>	<i>Current [A]</i>	<i>Voltage [V]</i>	<i>Time [s]</i>	<i>Energy [kJ]</i>
RW1	5 W/cm ²	6 bar	15.29	8.07	140	1.73
RW2	6 W/cm ²	6 bar	17.17	8.61	100	1.48
RW3	8 W/cm ²	6 bar	19.00	10.20	80	1.55

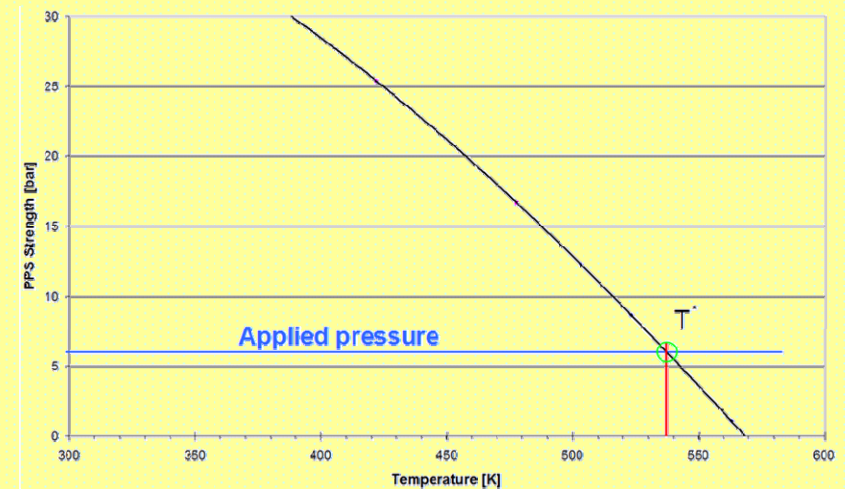
TPC RESISTANCE WELDING PROCESS: THE HEATING ZONE EVOLUTION

The heating zone subdomain change during the RW process



T^* = PPS resin parameters

T^* temperature intersection between the resin strength trend and the applied pressure



TPC RESISTANCE WELDING PROCESS:

THE TEMPERATURE PARAMETERS

TEMPERATURE
PARAMETERS

THERMAL MATERIAL PROPERTIES: k ,
 C_p , ρ

HEAT TRANSFER COEFFICIENT: *natural
convection coefficient*

Thermal properties evolution in the heating zone
evaluated by mixture phases equation:

$$X(T) = \boxed{X_R(T) + X_A(T)} + X_{MM}(T)$$

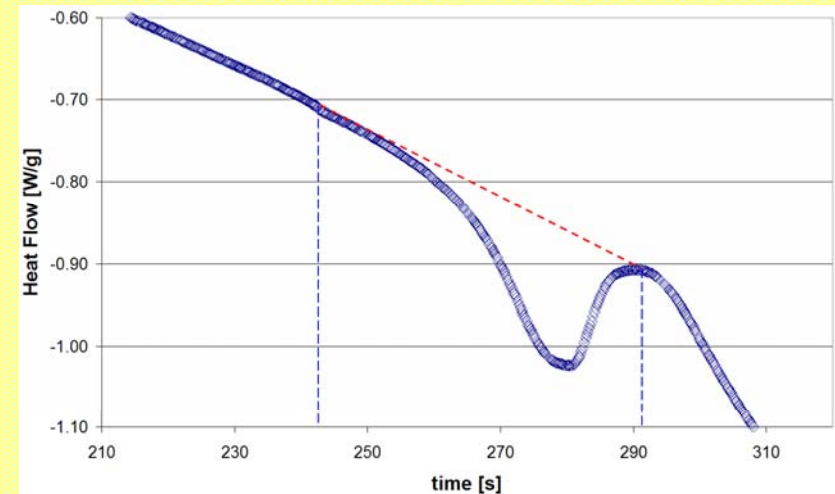
$$RA_f = \frac{V_{PPS}}{V_{TOT}} = f(T)$$

TPC RESISTANCE WELDING PROCESS:

LATENT HEAT IN THE MELTING PROCESS

The thermoplastic resin need heat to break the polymer link during the heating process.

D.S.C. (Differential Scanning Calorimetric) analysis allowed a heat flow valuation in the heating of PPS resin sample



From experimental measurement was accounted an heat sink in the heating zone

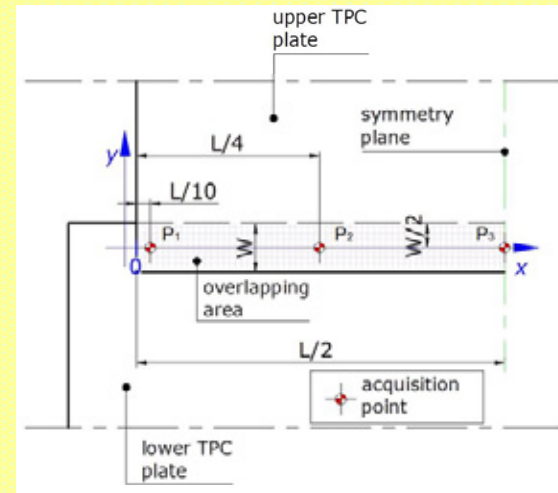
*Volumetric heat
flow assorbition*

$$Q_{abs} = \dot{Q} \rho_{PPS}$$

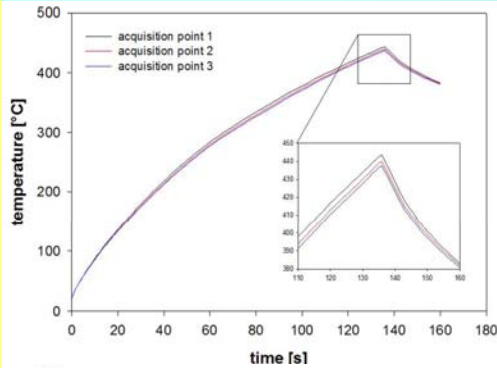
*Mass heat flow
assorbition*

TPC RESISTANCE WELDING PROCESS: NUMERICAL RESULTS

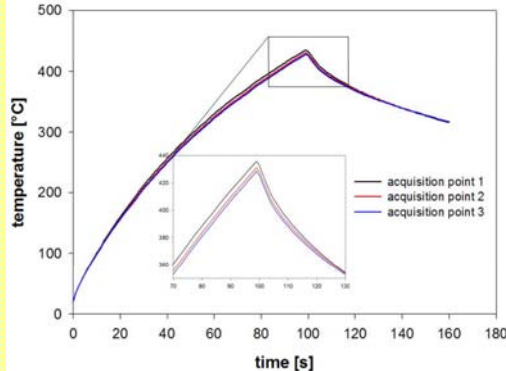
The temperature – time profiles were reported for three points P1, P2, P3



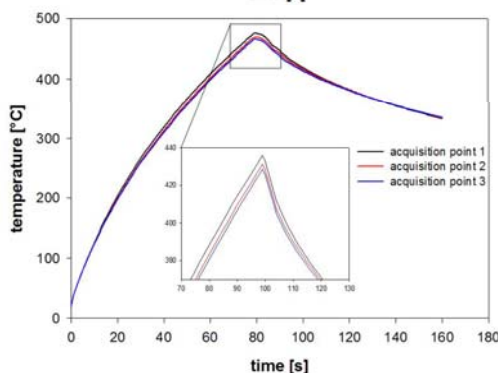
RW1



RW2

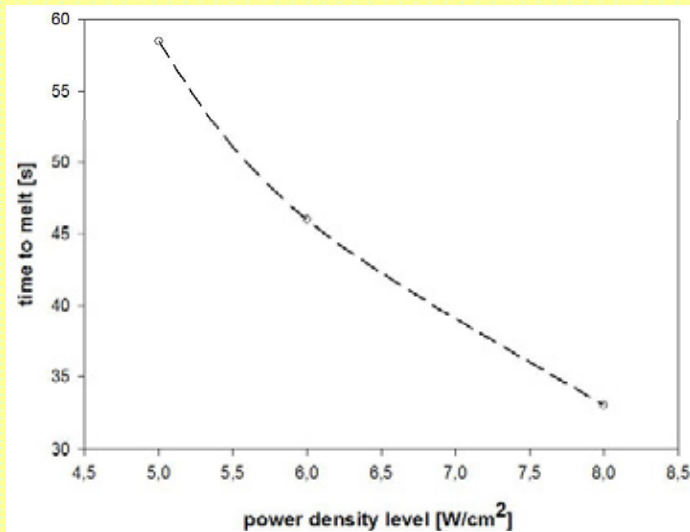


RW3



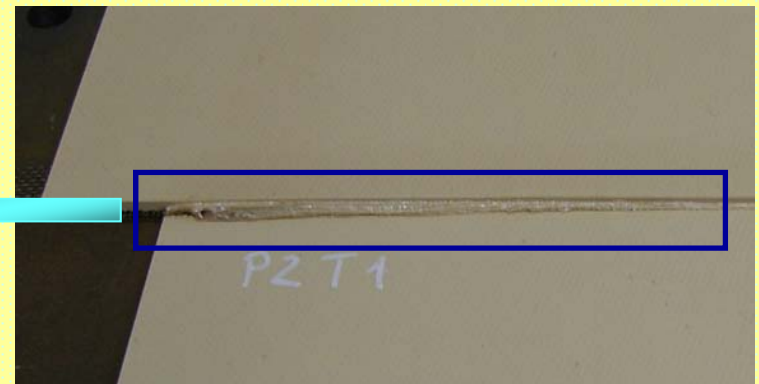
- the leakage phenomenon \Rightarrow high temperature close to the ends in the overlapping zone
- higher temperature for higher electric power density level though the process was the shorter one

TPC RESISTANCE WELDING PROCESS: NUMERICAL RESULTS

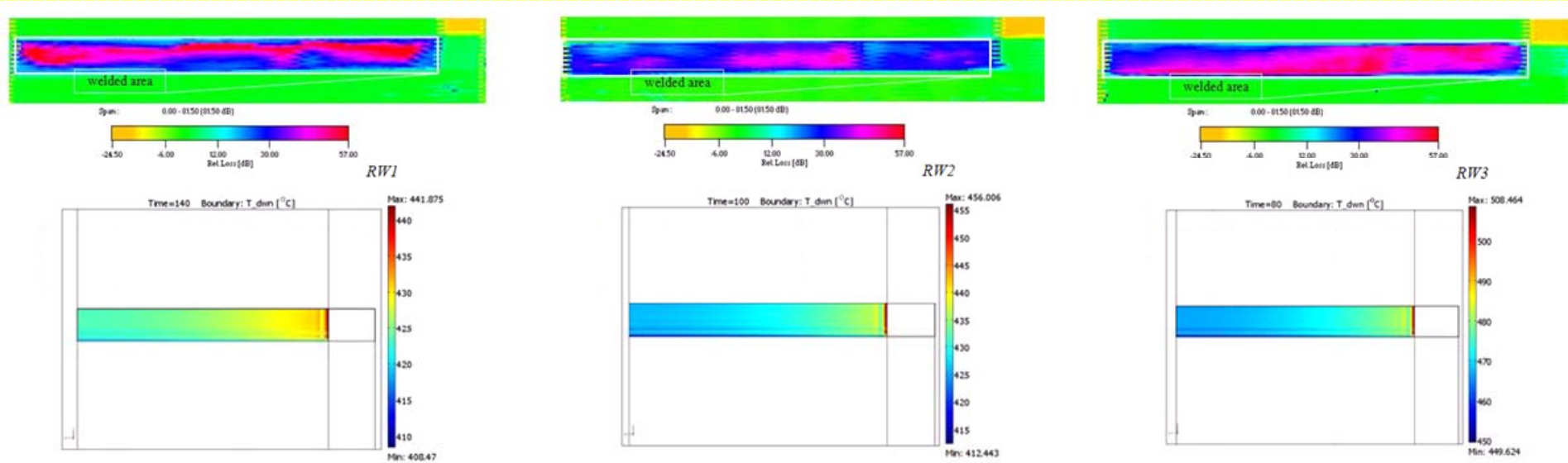


the time to melt showed theoretical “near hyperbolic” dependence from the electric applied power density

long process time together high power density result in a resin squeeze flow



TPC RESISTANCE WELDING PROCESS: NUMERICAL vs EXPERIMENTAL OBSERVATION



- Squeeze flow rise when resin temperature overcome its higher processing limit (380°C for PPS)
- The experimental results showed higher temperature prediction values

TPC RESISTANCE WELDING PROCESS: CONCLUSIONS

- A numerical *resistance welding* process for thermoplastic composite materials was modelled
- The *heating zone evolution* was accounted in the model by means a user defined Temperature dependent subdomain equation
- The numerical results allow to compare the influence of the **time process** and *electric power* applied level on the temperature distribution and the trend of *time to melt* on the applied electric power
- From experimental observation higher temperature prediction values were obtained by the simulations



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**THANK YOU VERY MUCH
FOR YOUR
ATTENTION**

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